

# Advanced Semiconductor Engineering, Inc.



## FOR IMMEDIATE RELEASE

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## ADVANCED SEMICONDUCTOR ENGINEERING, INC. ANNOUNCES MONTHLY NET REVENUES

TAIPEI, TAIWAN, R.O.C., FEBRUARY 9, 2007 – ADVANCED SEMICONDUCTOR ENGINEERING, INC. (NYSE: ASX, TAIEX: 2311, “ASE” or the “Company”), announces its unaudited consolidated net revenues for January 2007.

### CONSOLIDATED NET REVENUES (UNAUDITED)

(NT\$ Million)	Jan 2007	Dec 2006	Jan 2006	Sequential Change	YoY Change
Net Revenues	7,144	6,895	8,249	+3.61%	-13.40%

\* Starting from Jan. 1, 2007, Global Advanced Packaging Technology Limited (GAPT)'s revenues were consolidated into ASE Inc.'s consolidated revenues.

### Safe Harbor Notice:

This press release contains "forward-looking statements" within the meaning of Section 27A of the Securities Act of 1933, as amended, and Section 21E of the Securities Exchange Act of 1934, as amended. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these forward-looking statements, which apply only as of the date of this press release. The words "anticipate", "believe", "estimate", "expect", "intend", "plan" and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclical and market conditions in the semiconductor industry; demand for the outsourced semiconductor packaging and testing services we offer and for such outsourced services generally; the highly competitive semiconductor industry; our ability to introduce new packaging, interconnect materials and testing technologies in order to remain competitive; our ability to successfully integrate pending and future mergers and acquisitions; international business activities; our business strategy; general economic and political conditions; possible disruptions in commercial activities caused by natural or human-induced disasters; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People's Republic of China; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2005 Annual Report on Form 20-F filed on June 19, 2006.